

Data Sheet

FEATURES:

- High Gain:
 - Typically 32 dB gain across 2.4–2.5 GHz over temperature 0°C to +85°C
- · High linear output power:
 - >29 dBm P1dB
 - Please refer to "Absolute Maximum Stress Ratings" on page 4
 - Meets 802.11g OFDM ACPR requirement up to 25 dBm
 - Added EVM~4% up to 23 dBm for 54 Mbps 802.11g signal
 - Meets 802.11b ACPR requirement up to 25 dBm
- High power-added efficiency/Low operating current for both 802.11g/b applications
 - $\sim 26\%/300 \text{ mA } @ P_{OUT} = 24 \text{ dBm for } 802.11g$
 - $\sim 27\%/350 \text{ mA } @ P_{OUT} = 25 \text{ dBm for } 802.11\text{ b}$
- Built-in Ultra-low I_{REF} power-up/down control
 - I_{RFF} ~2 mA
- Low idle current
 - ~80 mA I_{CQ}

• High-speed power-up/down

- Turn on/off time (10%-90%) <100 ns
- Typical power-up/down delay with driver delay included <200 ns
- High temperature stability
 - ~1 dB gain/power variation between 0°C to +85°C
 - ~1 dB detector variation over 0°C to +85°C
- Low shut-down current (~1 μA)
- · On-chip power detection
- 25 dB dynamic range on-chip power detection
- Simple input/output matching
- · Packages available
 - 16-contact VQFN (3mm x 3mm)
- All non-Pb (lead-free) devices are RoHS compliant

APPLICATIONS:

- WLAN (IEEE 802.11g/b)
- Home RF
- · Cordless phones
- 2.4 GHz ISM wireless equipment

PRODUCT DESCRIPTION

The SST12LP15A is a high-power and high-gain power amplifier based on the highly-reliable InGaP/GaAs HBT technology.

The SST12LP15A can be easily configured for high-power applications with superb power-added efficiency while operating over the 2.4-2.5 GHz frequency band. It typically provides 32 dB gain with 26% power-added efficiency @ $P_{OUT} = 24$ dBm for 802.11g and 27% power-added efficiency @ $P_{OUT} = 25$ dBm for 802.11b.

The SST12LP15A has excellent linearity, typically ~4% added EVM at 23 dBm output power which is essential for 54 Mbps 802.11g operation while meeting 802.11g spectrum mask at 25 dBm. SST12LP15A also has wide-range (>25 dB), temperature-stable (~1 dB over 85°C), single-ended/differential power detectors which lower users' cost on power control.

The power amplifier IC also features easy board-level usage along with high-speed power-up/down control. Ultra-low reference current (total I_{REF} ~2 mA) makes the SST12LP15A controllable by an on/off switching signal directly from the baseband chip. These features coupled with low operating current make the SST12LP15A ideal for the final stage power amplification in battery-powered 802.11g/b WLAN transmitter applications.

The SST12LP15A is offered in 16-contact VQFN package. See Figure 2 for pin assignments and Table 1 for pin descriptions.

Data Sheet

FUNCTIONAL BLOCKS

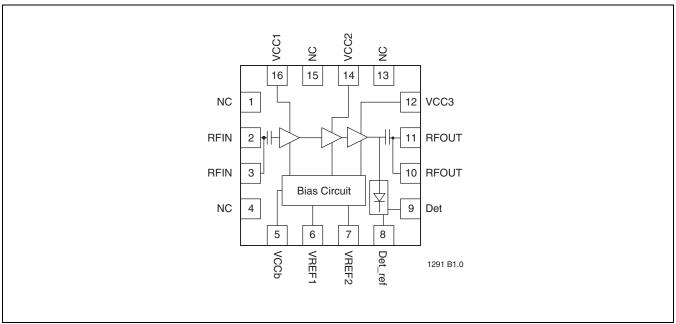


FIGURE 1: Functional Block Diagram6



PIN ASSIGNMENTS

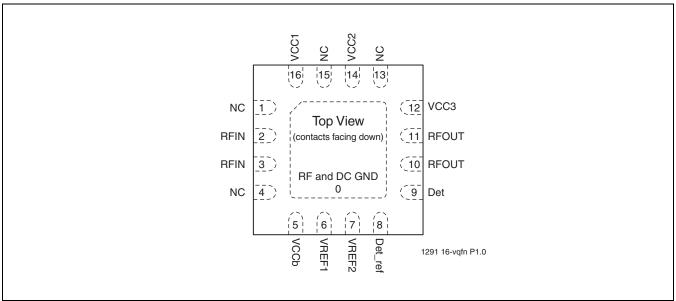


FIGURE 2: Pin Assignments for 16-contact VQFN

PIN DESCRIPTIONS

TABLE 1: Pin Description

Symbol	Pin No.	Pin Name	Type ¹	Function	
GND	0	Ground		The center pad should be connected to RF ground with several low inductance, low resistance vias.	
NC	1	No Connection		Unconnected pins.	
RFIN	2		I	RF input, DC decoupled	
RFIN	3		I	RF input, DC decoupled	
NC	4	No Connection		Unconnected pins.	
VCCb	5	Power Supply	PWR	Supply voltage for bias circuit	
VREF1	6		PWR	1st and 2nd stage idle current control	
VREF2	7		PWR	3rd stage idle current control	
Det_ref	8		0	On-chip power detector reference	
Det	9		0	On-chip power detector	
RFOUT	10		0	RF output	
RFOUT	11		0	RF output	
VCC3	12	Power Supply	PWR	Power supply, 3rd stage	
NC	13	No Connection		Unconnected pins.	
VCC2	14	Power Supply	PWR	Power supply, 2nd stage	
NC	15	No Connection		Unconnected pins.	
VCC1	16	Power Supply	PWR	Power supply, 1st stage	

1. I=Input, O=Output

T1.0 1291



Data Sheet

ELECTRICAL SPECIFICATIONS

The AC and DC specifications for the power amplifier interface signals. Refer to Table 2 for the DC voltage and current specifications. Refer to Figures 3 through 10 for the RF performance.

Absolute Maximum Stress Ratings (Applied conditions greater than those listed under "Absolute Maximum Stress Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.)

Input power to pins 2 and 3 (P _{IN})	+5 dBm
Average output power (P _{OUT}) ¹	+28 dBm
Supply Voltage at pins 5, 12, 14, 16 (V _{CC})	0.3V to +4.6V
Reference voltage to pins 6 (V _{REF1}) and pin 7 (V _{REF2})	0.3V to +3.6V
DC supply current (I _{CC})	500 mA
Operating Temperature (T _A)	40°C to +85°C
Storage Temperature (T _{STG})	40°C to +120°C
Maximum Junction Temperature (T _J)	+150°C
Surface Mount Solder Reflow Temperature	

^{1.} Never measure with CW source. Pulsed single-tone source with <50% duty cycle is recommended. Exceeding the maximum rating of average output power could cause permanent damage to the device.

Operating Range

Range	Ambient Temp	V _{CC}		
Industrial	-40°C to +85°C	3.3V		

TABLE 2: DC Electrical Characteristics at 25°C

Symbol	Parameter	Min.	Тур	Max.	Unit
V _{CC}	Supply Voltage at pins 5, 12, 14, 16	3.0	3.3	4.2	V
I _{CC}	Supply Current				
	for 802.11g, 24 dBm		300		mA
	for 802.11b, 25 dBm		350		mA
I _{CQ}	Idle current for 802.11g to meet EVM<4% @ 23dBm		80		mA
I _{OFF}	Shut down current		1		μΑ
V _{REG1}	Reference Voltage for 1st and 2nd Stage, with 270Ω resistor	2.85	2.90	2.95	V
V _{REG2}	Reference Voltage for 3rd Stage, with 100Ω resistor	2.85	2.90	2.95	V

T2.1 1291



Data Sheet

TABLE 3: AC Electrical Characteristics for Configuration at 25°C

Symbol	Parameter	Min.	Тур	Max.	Unit
F _{L-U}	Frequency range in 802.11b/g applications (see Figure 11)	2400		2485	MHz
P _{OUT}	Output power				
	@ PIN = -10 dBm 11b signals		23		dBm
	@ PIN = -10 dBm 11g signals		23		dBm
G	Small signal gain	31	32		dB
G _{VAR1}	Gain variation over each band (2400-2485 MHz)			±0.5	dB
G _{VAR2}	Gain ripple over channel (Gain variation over 20 MHz)		0.2		dB
ACPR	Meet 11b spectrum mask	24	25		dBm
	Meet 11g OFDM 54 MBPS spectrum mask	24	25		dBm
Added EVM	@ 23 dBm output with 11g OFDM 54 MBPS signal		3.5		%
2f, 3f, 4f, 5f	Harmonics at 22 dBm, without trapping capacitors			-40	dBc

T3.2 1291



TYPICAL PERFORMANCE CHARACTERISTICS

Test Conditions: $V_{CC} = 3.3V$, $T_A = 25^{\circ}C$ Unless otherwise specified.

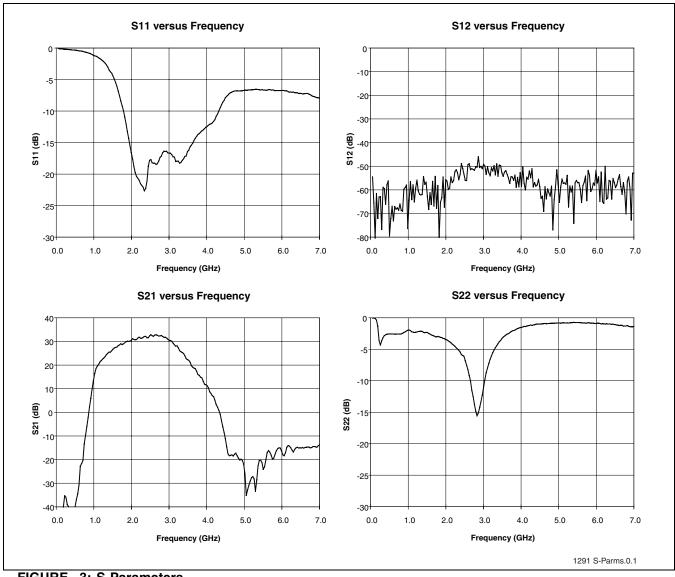


FIGURE 3: S-Parameters



TYPICAL PERFORMANCE CHARACTERISTICS Test Conditions: $V_{CC} = 3.3V$, $T_A = 25^{\circ}C$, 54 Mbps 802.11g OFDM Signal

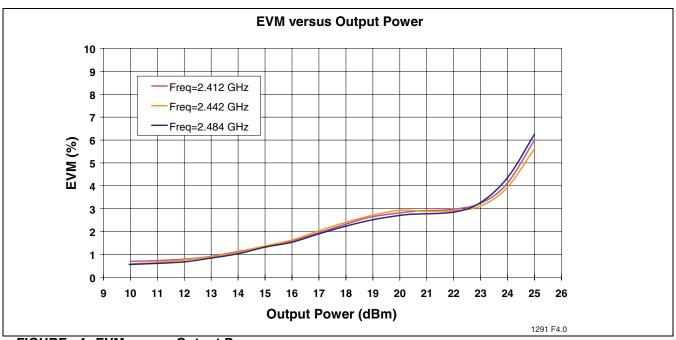


FIGURE 4: EVM versus Output Power

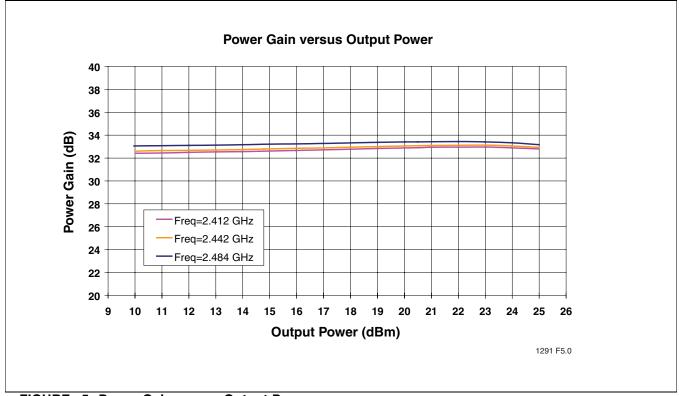


FIGURE 5: Power Gain versus Output Power



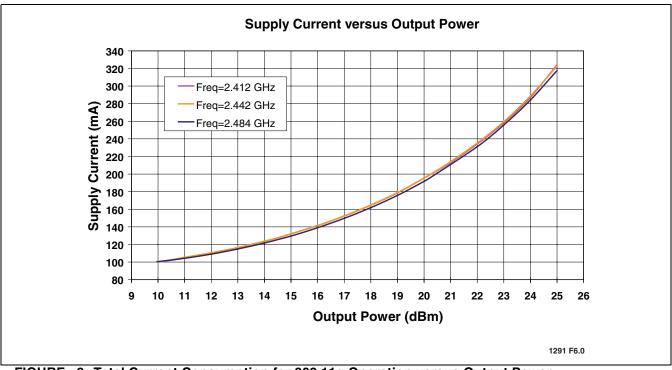


FIGURE 6: Total Current Consumption for 802.11g Operation versus Output Power

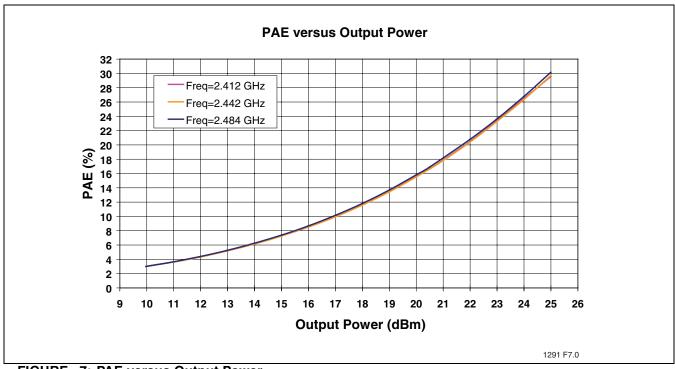


FIGURE 7: PAE versus Output Power



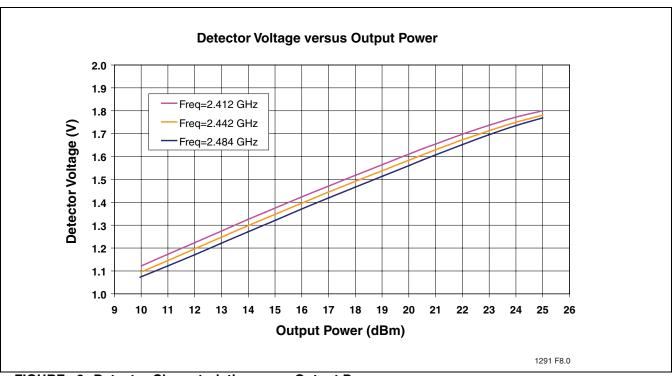


FIGURE 8: Detector Characteristic versus Output Power

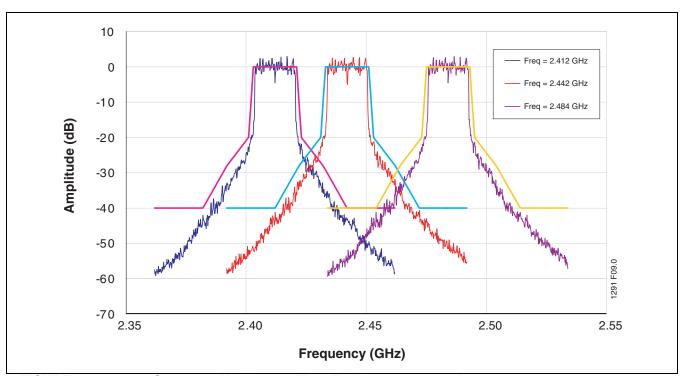


FIGURE 9: 802.11g Spectrum Mask at 24 dBm, Total current 300 mA



TYPICAL PERFORMANCE CHARACTERISTICS Test Conditions: $V_{CC} = 3.3V$, $T_A=25^{\circ}C$, 1 Mbps 802.11b CCK signal

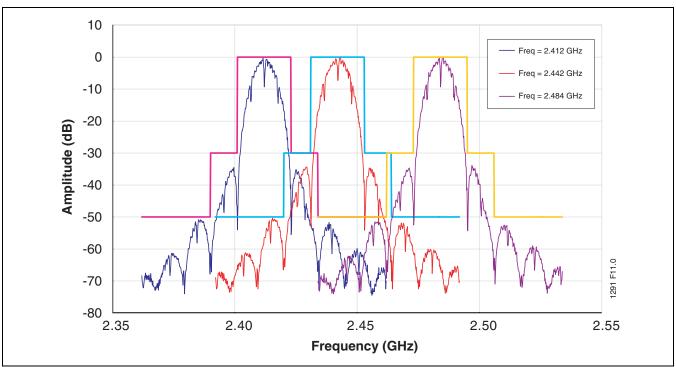


FIGURE 10: 802.11b Spectrum Mask at 25 dBm, Total current 350 mA

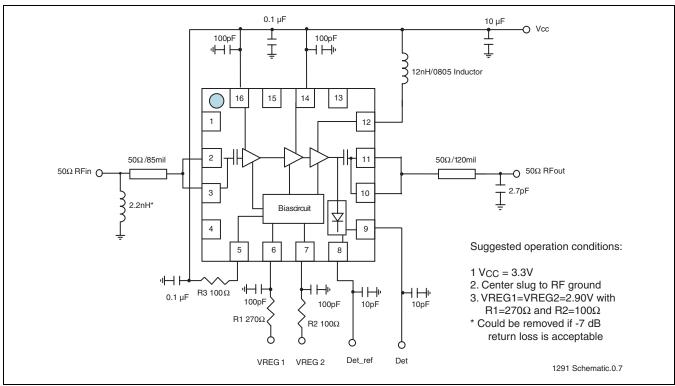
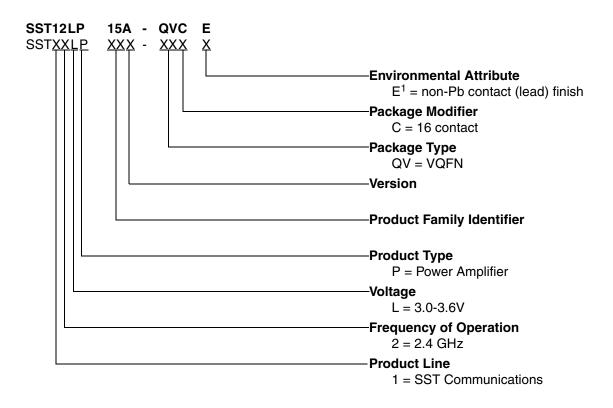


FIGURE 11: Typical Schematic for High-Power, High-Efficiency 802.11b/g Applications



PRODUCT ORDERING INFORMATION



Environmental suffix "E" denotes non-Pb solder. SST non-Pb solder devices are "RoHS Compliant".

Valid combinations for SST12LP15A

SST12LP15A-QVCE

SST12LP15A Evaluation Kits

SST12LP15A-QVCE-K

Note: Valid combinations are those products in mass production or will be in mass production. Consult your SST sales representative to confirm availability of valid combinations and to determine availability of new combinations.

Data Sheet

PACKAGING DIAGRAMS

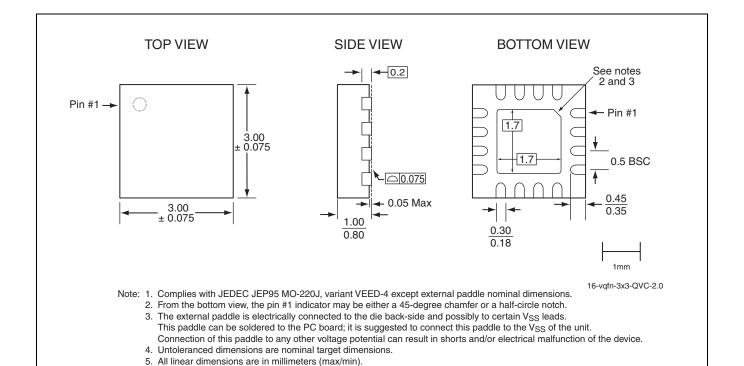


FIGURE 12: 16-contact Very-thin Quad Flat No-lead (VQFN)
SST Package Code: QVC

TABLE 4: Revision History

Revision	Description	Date
00	Initial release of data sheet	Mar 2005
01	Updated values for gain and efficiency on page 1	Mar 2006
	Updated values for VREG1 and VREG2 in Table 2 on page 4	
	Removed stability parameter from Table 3 on page 5	
	Updated the typical application schematic on page 10	
	Updated QVC package drawing.	
	Updated "Absolute Maximum Stress Ratings" on page 4	
02	Added information for 2.3-2.4 and 2.5-2.6 applications	Jul 2006
	Removed leaded part numbers	
03	Updated "Features:" and "Product Description" on page 1	Sep 2008
	Revised Table 2 on page 4 and Table 3 on page 5	
	Updated values in Figure 11 on page 10.	
	Removed two schematics	
	Updated Figures 3 - 8	
04	Updated "Contact Information" on page 13.	Feb 2009



Data Sheet

CONTACT INFORMATION

Marketing

SST Communications Corp.

5340 Alla Road, Ste. 210 Los Angeles, CA 90066 Tel: 310-577-3600

Fax: 310-577-3605

Sales and Marketing Offices

NORTH AMERICA

Silicon Storage Technology, Inc.

1171 Sonora Court Sunnyvale, CA 94086-5308

Tel: 408-735-9110 Fax: 408-735-9036

EUROPE

Silicon Storage Technology Ltd.

Mark House 9-11 Queens Road Hersham, Surrey KT12 5LU UK

Tel: 44 (0) 1932-238133 Fax: 44 (0) 1932-230567

JAPAN

SST Japan

NOF Tameike Bldg, 9F 1-1-14 Akasaka, Minato-ku Tokyo, Japan 107-0052 Tel: 81-3-5575-5515 Fax:81-3-5575-5516

ASIA PACIFIC NORTH

SST Macao

Room N, 6th Floor, Macao Finance Center, No. 202A-246, Rua de Pequim, Macau

Tel: 853-2870-6022 Fax: 853-2870-6023

ASIA PACIFIC SOUTH

SST Communications Co.

16F-6, No. 75, Sec.1, Sintai 5th Rd Sijhih City, Taipei County 22101 Taiwan, R.O.C.

Tel: 886-2-8698-1198 Fax: 886-2-8698-1190

KOREA

SST Korea

6F, Heungkuk Life Insurance Bldg 6-7 Sunae-Dong, Bundang-Gu, Sungnam-Si Kyungki-Do, Korea, 463-020

Tel: 82-31-715-9138 Fax: 82-31-715-9137